HEPCO, Inc. 150 SAN LAZARO AVE., SUNNYVALE, CA 94086-5209 • (408) 738-1880 • FAX (408) 732-4456

Electronic Component Lead Cut & Form Equipment and BGA Reballing Systems

www.hepcoblue.com

Tired of throwing away rare or costly BGA/CSP devices? Can't wait days for someone else to reball your parts?

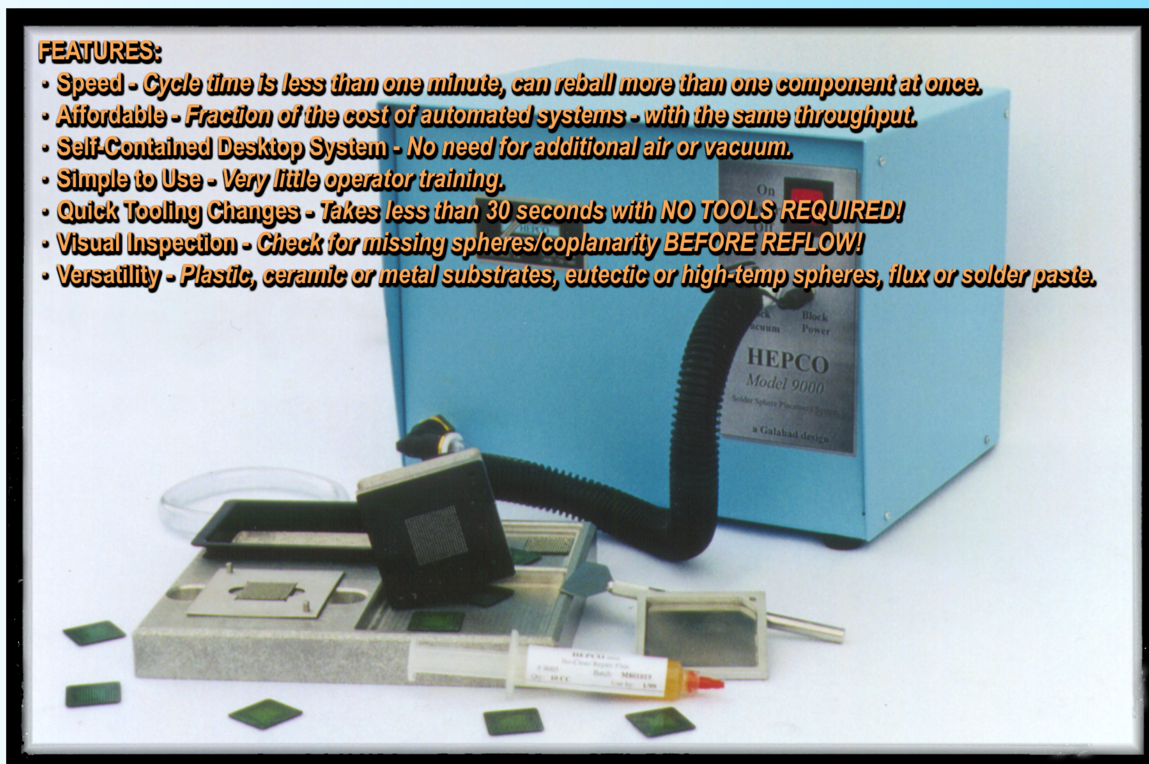
Let **HEPCO's Reballing System** speed up your process and ***improve your bottom line!***

HEPCO's patented Reballing Process can dramatically cut the cost and cycle time of Printed Circuit Assembly rework by giving **you** the power to **reball** your **PBGA, CBGA, µBGA, and CSP** packages at your facility. Imagine the huge cost advantage and quick-turn benefits having an in-house reballing capability will give you over your competitors! Whether you are building, repairing, or prototyping PCA's, HEPCO can provide the solution you need to quickly and easily reball almost any BGA/CSP device in less than one minute - and with a quality that rivals that of the highest-level equipment -
FOR LESS THAN $6,000!

Offer BGA/CSP reballing as a service… ***to your competitors!***

No longer will you have to pay an outside vendor to reball your components using slip-shod methods. No longer will you have to wait for days or even weeks for an outside vendor to order the tooling required to get the job done. You can control the process yourself, and insure the quality is up to your customers' standards - without having to hold up your whole project for days. And by taking advantage of HEPCO's new reduced-cost tooling options for different BGA/CSP Package layouts, you can tailor your order to fit your needs based on projected demand -
WITHOUT HAVING TO PURCHASE ADDITIONAL TOOLING!

Ideal for prototyping, repair, or low-mid volume production!



The HEPCO Model 9000-1 BGA Reballing System uses a fast, accurate technology that places an ENTIRE ARRAY AT ONCE! If desired, tooling can be made to reball several components in one cycle, which saves even more time when you have to reball a significant volume of parts in a hurry. What's more, the HEPCO Reballing System can be used for Ceramic, Metal, or Plastic components, and even Micro-BGA's with sphere sizes as small as .012" (.3mm). Ask your current vendor how small they can go! HEPCO's unique system is compatible with Eutectic or High-Temp spheres, Flux or Solder Paste. Almost ANY combination of materials can be used. Call us today and ask our knowledgeable and friendly staff about your application.

HEPCO, Incorporated

150 San Lazaro Avenue - Sunnyvale, CA 94086 - (408) 738-1880 office - (408) 732-4456 fax
info@hepcoblue.com
www.hepcoblue.com